

0.8A Avg.

600 Volts

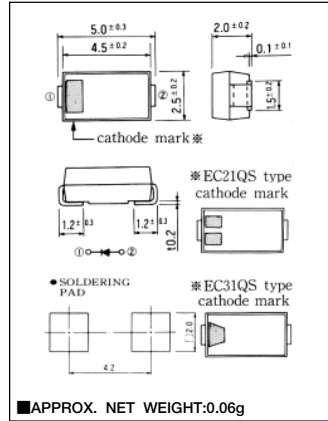
FRED

EC8FS6

■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
繰り返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	600	V
平均整流電流 Average Rectified Forward Current	I_O	50Hz, 正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	$T_a=25^{\circ}C^{*1}$ 0.65 A
			$T_a=35^{\circ}C^{*2}$ 0.8 A
実効順電流 R.M.S. Forward Current	$I_{F(RMS)}$	1.256	A
サージ順電流 Surge Forward Current	I_{FSM}	20 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150	$^{\circ}C$
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	$^{\circ}C$

■OUTLINE DRAWING(mm)



■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit	
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^{\circ}C, V_{RM}=V_{RRM}$	—	—	20	μA	
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^{\circ}C, I_{FM}=0.8A$	—	—	1.32	V	
逆回復時間 Reverse Recovery Time	t_{rr}	$I_{FM}=1A, -di/dt=50 A/\mu s, T_j=25^{\circ}C$	—	—	80	ns	
		$T_a=25^{\circ}C, I_F=I_R=10mA$	—	—	0.4	μs	
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	Glass Epoxy Substrate Mounted*1		—	157	$^{\circ}C/W$
			Alumina Substrate Mounted*2		—	108	$^{\circ}C/W$

*1:プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands= 2×2 mm, Both Sides)
*2:アルミナ基板実装/Alumina Substrate mounted (Soldering Lands= 2×2 mm, Both Sides)

■定格・特性曲線

